

# Electro-Science Laboratories, Inc.

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# **CERMET GOLD CONDUCTOR**

8836 8836-A

ESL 8836 and 8836-A mixed bonded thick film gold pastes are specially designed for thin printing. They produce a very smooth, dense film of 6 to 9 micrometers fired thickness. ESL 8836 is particularly well suited for automatic thermosonic wirebonding. While they have a wide firing range, a peak firing temperature of 850°C gives the best properties.

ESL 8836-A is an alloyed version of 8836. Its properties are similar to 8836, but it is designed for ultrasonic wire bonding using 25 micrometers diameter aluminum wire.

## **PASTE DATA**

RHEOLOGY: Thixotropic, screen printable paste

VISCOSITY:

250±25 Pa·s (Brookfield RVT, ABZ Spindle, 10 rpm, 25.5°C±0.5°C)

**BONDING MECHANISM:** Mixed

SHELF LIFE: (25°C) 6 months

### **PROCESSING**

**SCREEN MESH/EMULSION:**  $325/25 \mu m$ 

**LEVELING TIME: (25°C)** 5-10 minutes

DRYING AT 125°C: 10-15 minutes

FIRING TEMPERATURE RANGE: 850°C-930°C

> **OPTIMUM:** 850°C

> TIME AT PEAK: 10-12 minutes

RATE OF ASCENT/DESCENT: 60°C-100°C/minute

SUBSTRATE OF CALIBRATION: 96% alumina

THINNER: ESL 413

8836/A 9711-E

**ESL Affiliates** 

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#### TYPICAL PROPERTIES

FIRED THICKNESS: 6-9 μm

**RESISTIVITY:** 8836  $\leq$  6 m $\Omega$ /square

**8836-A**  $\leq$  10 m $\Omega$ /square

**PRINTING RESOLUTION:** 

(Line/Space) 125  $\mu$ m x 125  $\mu$ m

**APPROXIMATE COVERAGE:** 80-85 cm<sup>2</sup>/gram

ADHESION: (90° pull, 2.0 mm x 2.0 mm pads, 80 Au/20 Sn solder)

Initial pull strength: 30-40 N

Aged 48 hours at 150°C:  $\geq$  20 N

THERMOSONIC WIRE BONDING:

(125°C bonding temperature)

(25 μm Au) **8836** 6-9 grams

**8836-A** 5-8 grams

(50 μm Au) **8836** 20-26 grams

**8836-A** 19-25 grams

**ULTRASONIC AI WIRE BOND:** 

(25 µm, 1% Si, Al wire)

Initial pull strength: 8836 7-9 grams

**8836-A** 6-10 grams

**Aged 48 hours at 150°C: 8836** 4-7 grams

**8836-A** 5-6 grams

**Aged 200 hours at 150°C:** 8836 3-4 grams

**CONTACT RESISTANCE:** 

(Change in contact resistance of Al bonds, 1000 hours at 150°C)

8836-A Insignificant

EUTECTIC DIE BONDING: Excellent

**COMPATIBILITY:** ESL 3900, 3980, R-300-A and D-R-300-B

ESL 4905-C, 4905-CH, 4911

8836/A 9711-E

CAUTION: Proper industrial safety precautions should be exercised in using these products. Use with adequate ventilation. Avoid prolonged contact with skin or inhalation of any vapors emitted during use or heating of these compositions. The use of safety eye goggles, gloves or hand protection creams is recommended. Wash hands or skin thoroughly with soap and water after using these products. Do not eat or smoke in areas where these materials are used. Refer to appropriate MSDS sheet.

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